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Applicant: Takeshi HASHIMOTO et al.

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Title: THERMOSETTING LOW-DIELECTRIC RESIN COMPOSITION AND USE THEREOF

Receipt of the following papers is acknowledged:

1. Utility Patent Application Transmittal (Rule 53(b) divisional of USSN 09/433,281, filed November 3, 1999)
2. Patent Office Fee Transmittal Form [in duplicate]
3. Specification comprising pages (including claims 1-11 and abstract)
4. Copy of executed Declaration and Power of Attorney from parent application
5. Information Disclosure Statement and Form PTO 1449
6. Claim of Priority Under 35 USC 119
7. Check in the amount of \$740.00.



Date: December 31, 2001

Attorney: MJ/pjm

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